

04-15-05

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.: 10/779,563
Filing Date: February 16, 2004
Applicant: Yoshiro Iwasa
Group Art Unit: Unknown
Examiner: Unknown
Title: LEAD FRAME, SEMICONDUCTOR CHIP PACKAGE,
METHOD FOR MANUFACTURING SEMICONDUCTOR
DEVICE, AND SEMICONDUCTOR DEVICE
Attorney Docket: 9319S-000666

U.S. Patent and Trademark Office
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Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Reply to NOTICE UNDER 37 CFR 1.251 – Pending Application

Sir:

In response to the above-identified notice mailed April 7, 2005, Applicant has reviewed its files and states that no Information Disclosure Statement was filed on 06/16/04. An Information Disclosure Statement was, however, mailed to the PTO along with the original application papers on February 16, 2004. A duplicate copy of that IDS and the references are enclosed.

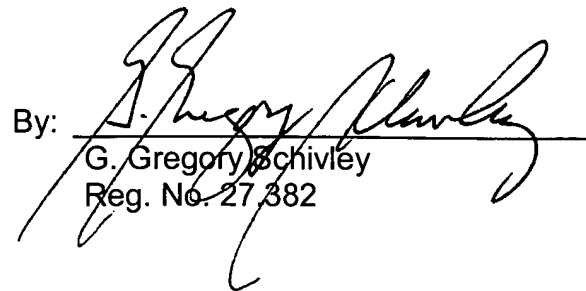
EV 570 162 508 US



Favorable consideration of this application is respectfully requested.

Respectfully submitted,

Dated: April 14, 2005

By: 
G. Gregory Schivley
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